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Cryocooler-based conduction cooling has gained traction in replacing liquid He baths for cooling in applications such as superconducting radiofrequency cavities. One of the primary governing factors in conduction cooling is thermal contact resistance (R_c) between two different metals, which, for example, varies from 10⁻⁴ to 10⁻³ m²K/W near 4 K for a bolting force of 3 to 10 kN between high-purity aluminum and niobium. However, the measured R_c is far from the intrinsic R_c expected of metal contact, thus leading to losses at the contact. With the present study, we aim to measure the intrinsic R_c between two distinct materials using time-resolved EUV diffraction measurements. The intrinsic value will serve as a benchmark for evaluating the thermal contact's effectiveness, which is currently lacking. The sensitivity of our setup is 10^{-9} m²K/W and surpasses the existing reported values by order of magnitudes.



Thermal contact resistance using time-resolved EUV diffraction- a novel technique to study conduction-cooled superconducting RF cavity

